

A2
27. (Amended) The plating apparatus according to claim 26, further comprising a cleaning unit for cleaning the plated substrate taken out of said substrate holder.

35. (Amended) A plating apparatus for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

A3
a cassette table for loading a cassette housing the substrate therein;
a pre-wetting tank for applying a pre-wetting treatment to the substrate to increase the wettability thereof;
a plating tank for plating the substrate after the pre-wetting treatment;
a cleaning unit for cleaning the plated substrate;
a drying unit for drying the cleaned substrate;
a deaerating unit for deaerating a liquid used for the pre-wetting treatment; and
a substrate transferring device for transferring the substrate.

A4
40. (Amended) The plating apparatus according to claim 39, further comprising a cleaning unit for cleaning the plated substrate taken out of said substrate holder.

46. (Amended) An apparatus for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

A5
a cassette table for loading a cassette housing the substrate therein;
a pre-soaking tank for applying a pre-soaking treatment to the substrate;
a plating tank for plating the substrate after the pre-soaking treatment;
a cleaning unit for cleaning the plated substrate;
a drying unit for drying the cleaned substrate;
a deaerating unit for deaerating a liquid used for the pre-soaking treatment; and
a substrate transferring device for transferring the substrate.

A6
51. (Amended) The plating apparatus according to claim 50, further comprising a cleaning unit for cleaning the plated substrate taken out of said substrate holder.

A7
62. (Amended) The plating apparatus according to claim 61, further comprising a cleaning unit for cleaning the plated substrate taken out of said substrate holder.

67. (Amended) An apparatus for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

- A8
- a cassette table for loading a substrate cassette thereon;
 - a plating tank for plating the substrate;
 - a cleaning unit for cleaning the plated substrate;
 - a drying unit for drying the cleaned substrate;
 - a deaerating unit for deaerating a plating liquid;
 - an annealing unit for annealing the plated substrate; and
 - a substrate transferring device for transferring the substrate.

A9
70. (Amended) A method for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

- holding a substrate taken out of a cassette by a substrate holder;
- pre-wetting the substrate held by said substrate holder;
- plating the pre-wetted surface of the substrate by immersing the substrate together with said substrate holder in a plating liquid;
- cleaning the plated substrate together with said substrate holder; and
- taking the substrate out of said substrate holder and drying the substrate.

71. (Amended) A method for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

- holding a substrate taken out of a cassette by a substrate holder;

19
Add

pre-soaking the substrate held by said substrate holder;
plating the pre-soaked surface of the substrate by immersing the substrate together with
said substrate holder in a plating liquid;
cleaning the substrate together with said substrate holder; and
taking the substrate out of said substrate holder and drying the substrate.

Please add the following new claims:

72. The plating apparatus according to claim 21, wherein said deaerating unit is
provided in said plating tank or in a plating liquid circulating system.

73. The plating apparatus according to claim 35, wherein said deaerating unit is
provided in said pre-wetting tank or in a pre-wetting liquid circulating system.

74. The plating apparatus according to claim 46, wherein said deaerating unit is
provided in said pre-soaking tank or in a pre-soaking liquid circulating system.

75. The plating apparatus according to claim 67, wherein said deaerating unit is
provided in said plating tank or in a plating liquid circulating system.

76. The plating apparatus according to claim 27, wherein said cleaning unit has a
function for drying the plated substrate.

77. The plating apparatus according to claim 40, wherein said cleaning unit has a
function for drying the plated substrate.

78. The plating apparatus according to claim 51, wherein said cleaning unit has a
function for drying the plated substrate.

79. The plating apparatus according to claim 62, wherein said cleaning unit has a function for drying the plated substrate.

80. The plating method according to claim 70, wherein said plated substrate is dried together with said substrate holder after the cleaning treatment.

81. The plating method according to claim 71, wherein said plated substrate is dried together with said substrate holder after the cleaning treatment.
